



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



# HCM1A1 104

## Automotive grade High current power inductors



### Product features

- AEC-Q200 Grade 1 qualified
- High current carrying capacity
- Magnetically shielded, low EMI
- Frequency range up to 1 MHz
- Inductance range from 0.2  $\mu$ H to 100  $\mu$ H
- Current range from 1.5 A to 40 A
- 11.5 mm x 10.3 mm footprint surface mount-package in a 4.0 mm height
- Alloy powder core material
- Moisture Sensitivity Level (MSL): 1
- Halogen free, lead free, RoHS compliant

### Applications

- Body electronics
  - Central body control module
  - Vehicle access control system
  - Headlamps, tail lamps and interior lighting
  - Heating ventilation and air conditioning controllers (HVAC)
  - Doors, window lift and seat control
- Advanced driver assistance systems
  - Adaptive cruise control (ACC)
  - Automatic parking control
  - Collision avoidance system/ Car black box system
- Infotainment and cluster electronics
  - Audio subsystem: head unit and trunk amp
  - Digital instrument cluster
  - In-vehicle infotainment (IVI) and navigation
  - Port power/USB HUB for front and rear passengers
- Chassis and safety electronics
  - Airbag control unit
  - Electronic stability control system (ESC)
  - Electric parking brake
- Engine and Powertrain Systems
  - Electric pumps, motor control and auxiliaries
  - Powertrain control module (PCU)/Engine Control unit (ECU)
  - Transmission Control Unit (TCU)

### Environmental Data

- Storage temperature range (Component): -55 °C to +155 °C
- Operating temperature range: -55 °C to +155 °C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020 (latest revision) compliant



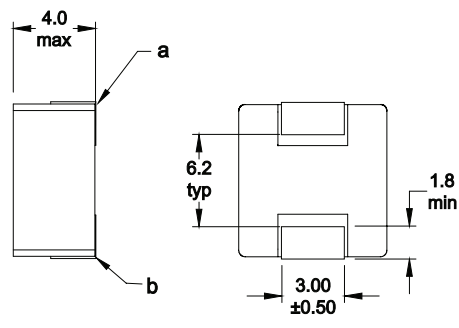
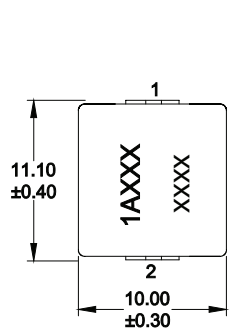
Product Specifications

Part Number <sup>6</sup>	OCL <sup>1</sup> ( $\mu\text{H}$ ) $\pm 20\%$	FLL <sup>2</sup> ( $\mu\text{H}$ ) minimum	$I_{\text{rms}}^3$ (A)	$I_{\text{sat}}^4$ (A)	DCR (m $\Omega$ ) typical @ +20 °C	DCR (m $\Omega$ ) maximum @ +20 °C	K-factor <sup>5</sup>
HCM1A1104-R20-R	0.20	0.13	33	40	0.63	0.72	902
HCM1A1104-R36-R	0.36	0.23	26	33	1.04	1.20	595
HCM1A1104-R45-R	0.45	0.29	25	32	1.07	1.23	490
HCM1A1104-R47-R	0.47	0.30	28.5	35	1.10	1.27	435
HCM1A1104-R56-R	0.56	0.36	22.5	24	1.56	1.8	453
HCM1A1104-R90-R	0.90	0.58	20	22	2.17	2.5	309
HCM1A1104-1R0-R	1.0	0.64	16	20	2.95	3.3	263
HCM1A1104-1R5-R	1.5	0.96	14	17	3.80	4.2	232
HCM1A1104-2R2-R	2.2	1.41	10.5	16	6.00	7.0	170
HCM1A1104-3R3-R	3.3	2.11	8.2	11.5	10.8	11.8	163
HCM1A1104-4R7-R	4.7	3.01	6.5	9.0	15	18	138
HCM1A1104-5R6-R	5.6	3.58	6.6	9.0	14	17	116
HCM1A1104-6R8-R	6.8	4.35	6.4	9.0	16	19	112
HCM1A1104-100-R	10	6.40	5.0	6.0	27	30	74
HCM1A1104-150-R	15	9.60	3.8	6.8	45	50	69
HCM1A1104-220-R	22	14.1	3.2	6.0	58	65	64
HCM1A1104-330-R	33	21.1	2.8	4.8	92	105	44
HCM1A1104-470-R	47	30.1	1.9	3.6	165	181	36
HCM1A1104-101-R	100	64.0	1.5	2.0	270	300	26

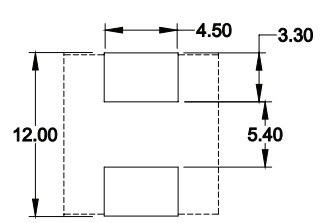
- Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.25  $V_{\text{max}}$ , 0.0 Adc, +25 °C
- Full Load Inductance (FLL) Test Parameters: 100 kHz, 0.25  $V_{\text{max}}$ ,  $I_{\text{sat}}$ , +25 °C
- $I_{\text{rms}}$ : DC current for an approximate temperature rise of 30 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 155 °C under worst case operating conditions verified in the end application.

- $I_{\text{sat}}$ : Peak current for approximately 20% rolloff @ +25 °C
- K-factor: Used to determine  $B_{\text{pp}}$  for core loss (see graph).  $B_{\text{p-p}} = K * L * \Delta I$ .  $B_{\text{pp}}$ : (Gauss), K: (K-factor from table), L: (Inductance in  $\mu\text{H}$ ),  $\Delta I$  (Peak to peak ripple current in Amps).
- Part Number Definition: HCM1A1104-xxx-R  
HCM1A1104 = Product code and size  
xxx= inductance value in  $\mu\text{H}$ , R= decimal point,  
If no R is present then last character equals number of zeros  
-R suffix = RoHS compliant

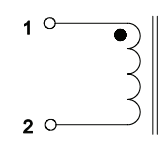
Dimensions (mm)



Recommended Pad Layout



Schematic

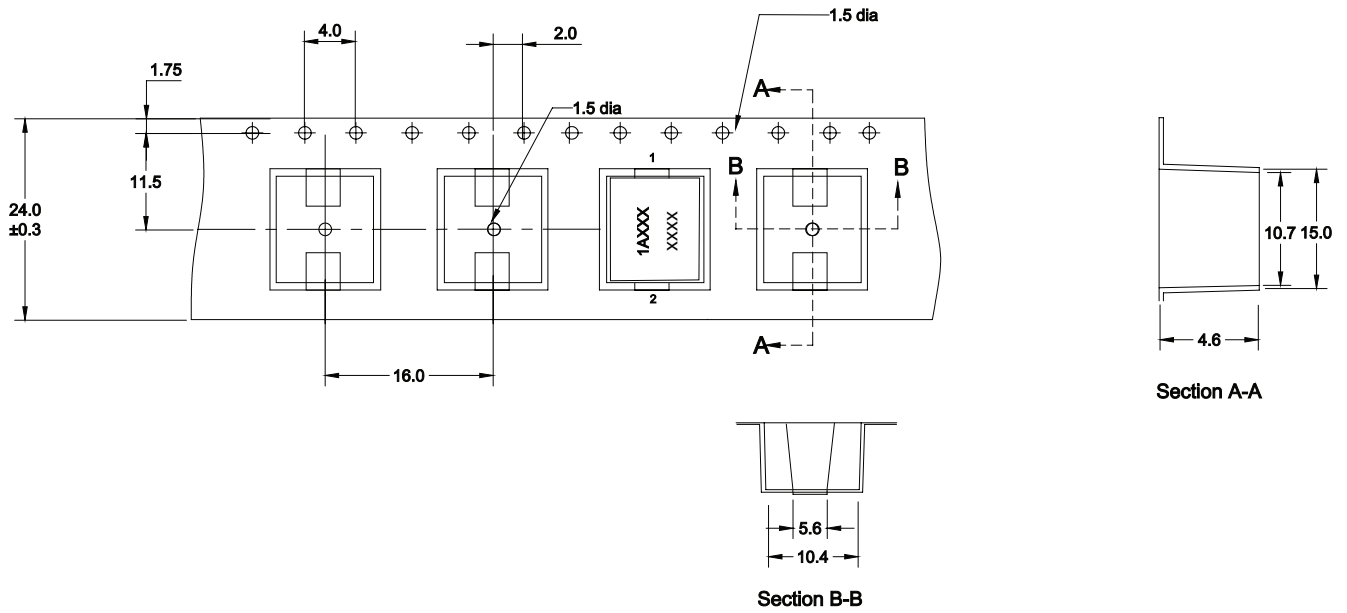


Part marking: 1AXXX=automotive grade, XXX=inductance value in uH, R=decimal point. If no R is present then last character equals number of zeros.  
xxxx=Lot code  
All soldering surfaces to be coplanar within 0.1 millimeters  
Tolerances are  $\pm 0.3$  millimeters unless stated otherwise  
DCR measured from point "a" to point "b"  
Color: Grey  
Do not route traces or vias underneath the inductor

**Packaging information (mm)**

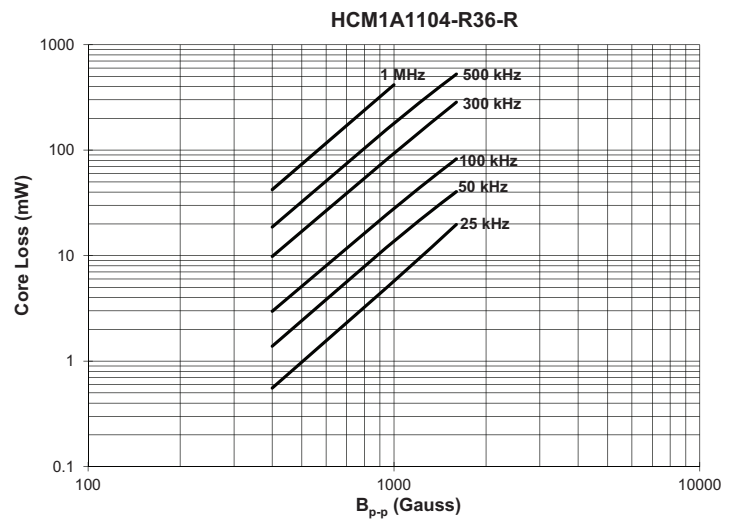
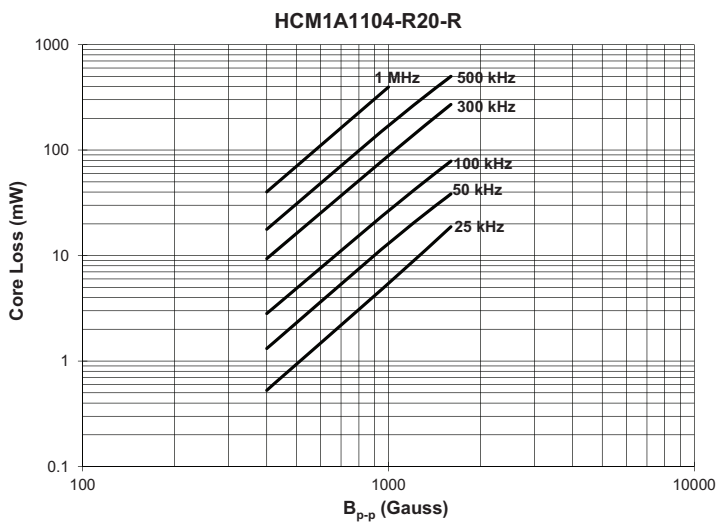
Drawing not to scale

Supplied in tape and reel packaging, 500 parts per 13" diameter reel

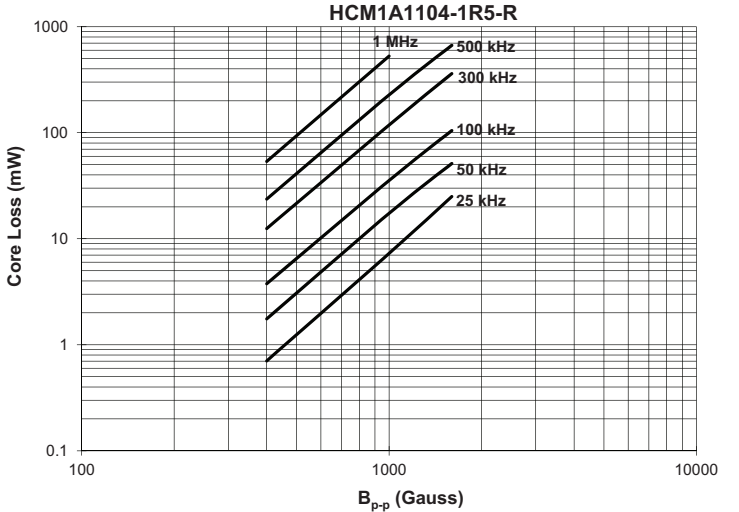
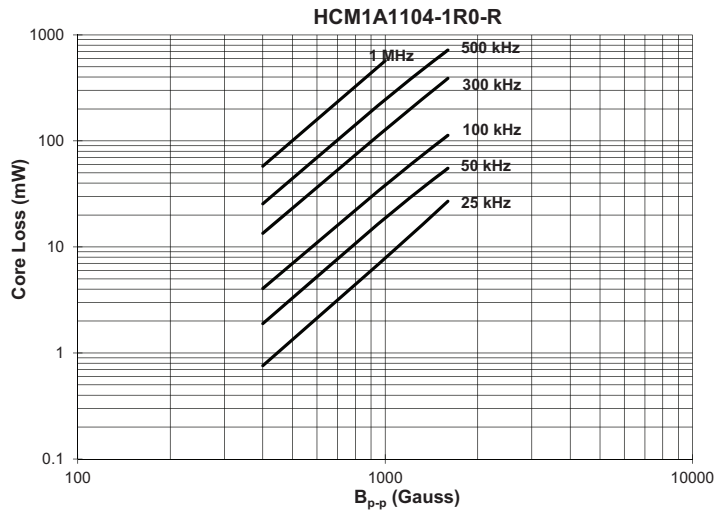
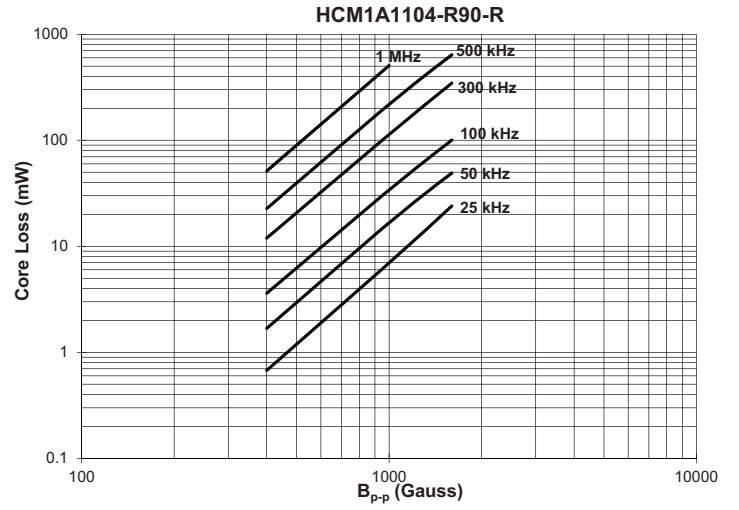
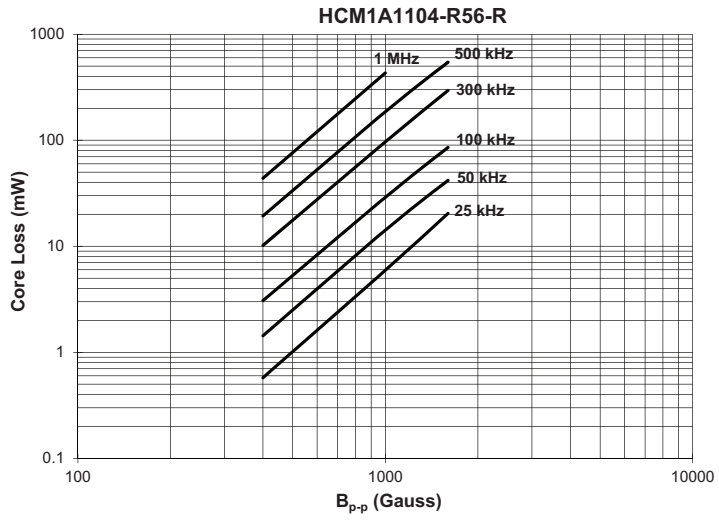
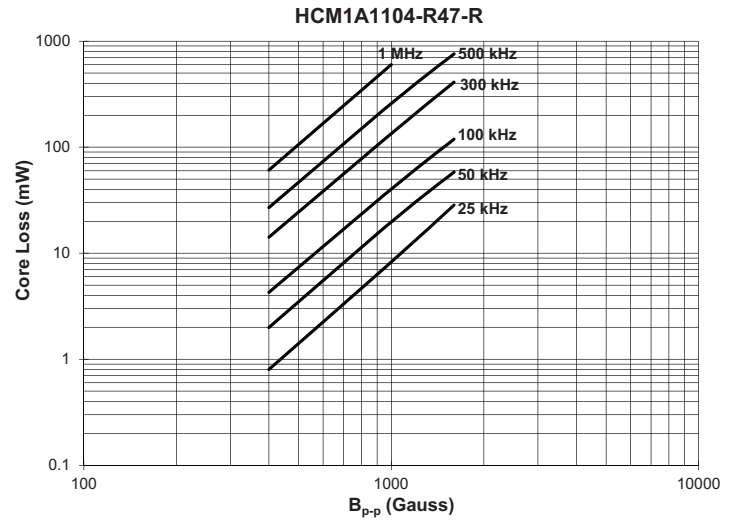
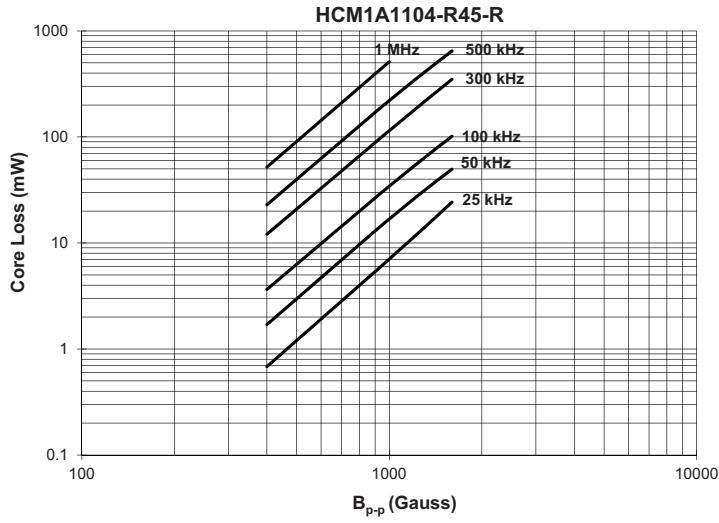


User direction of feed →

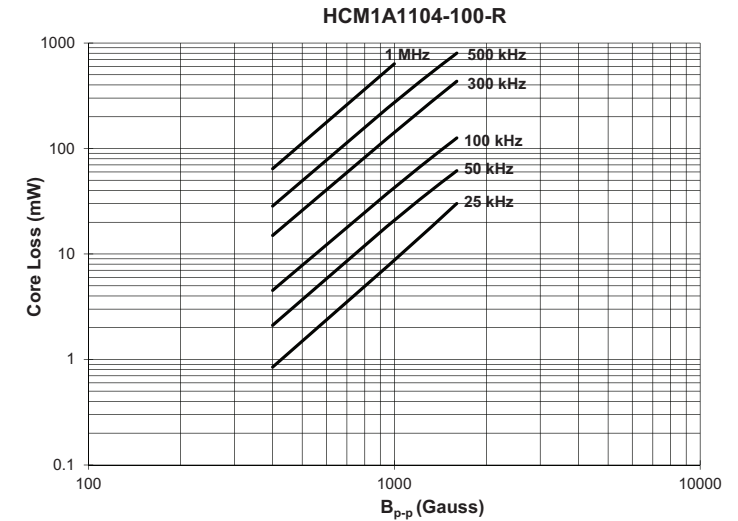
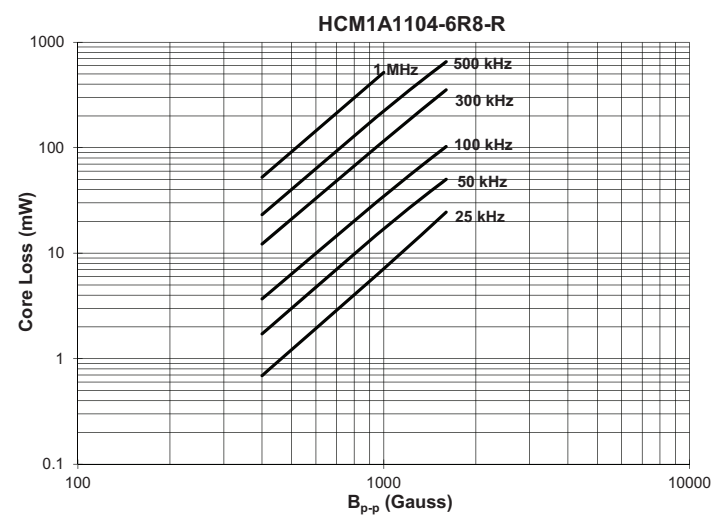
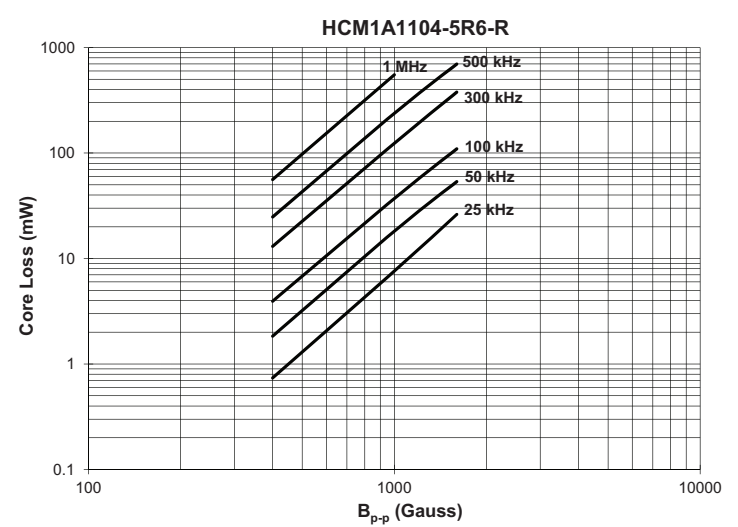
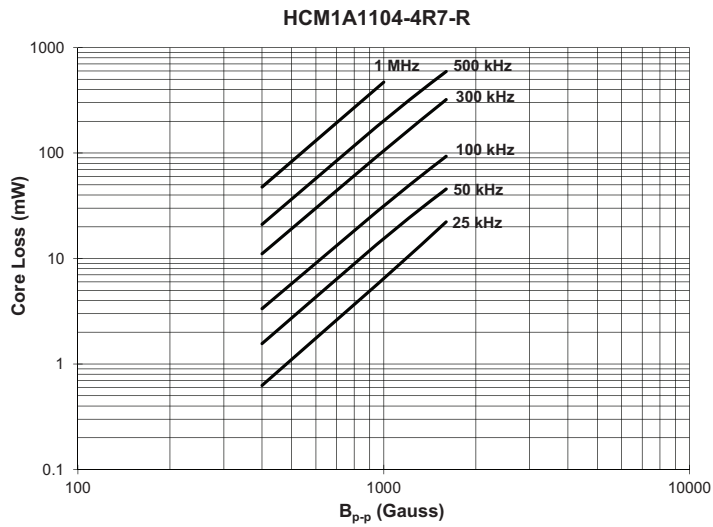
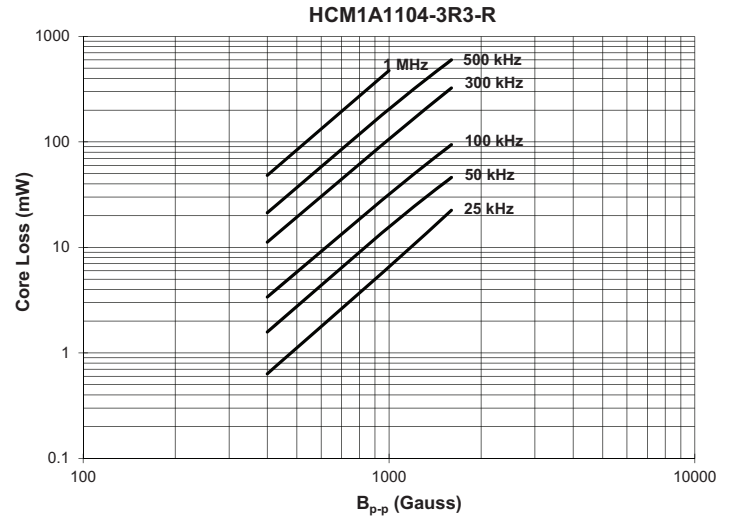
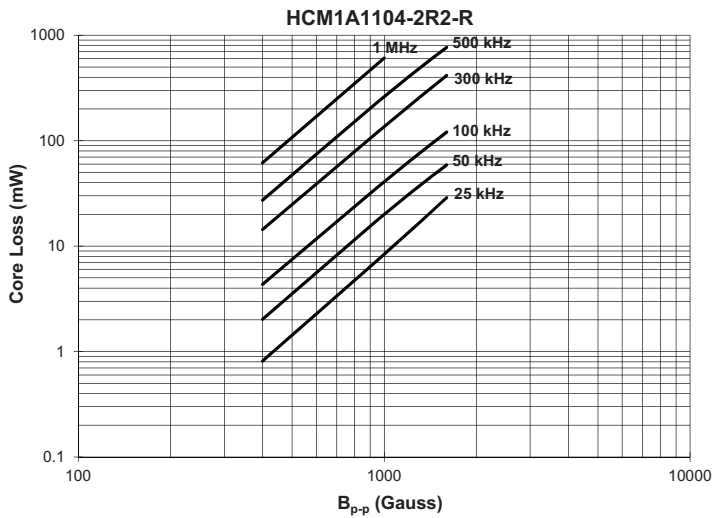
**Core loss vs  $B_{p-p}$**



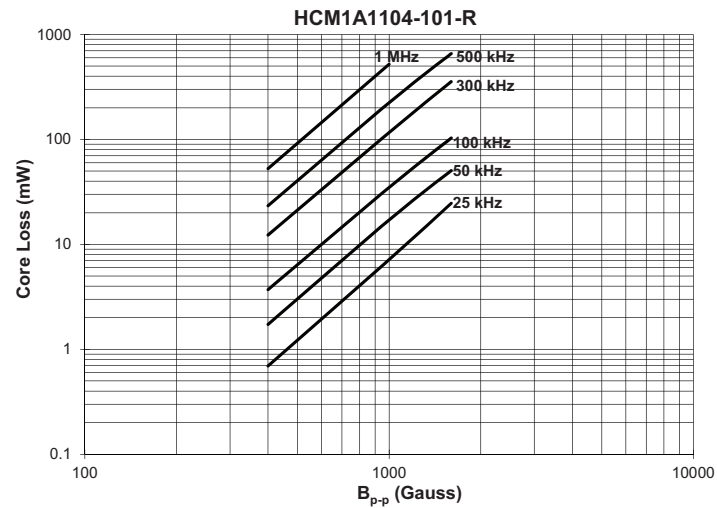
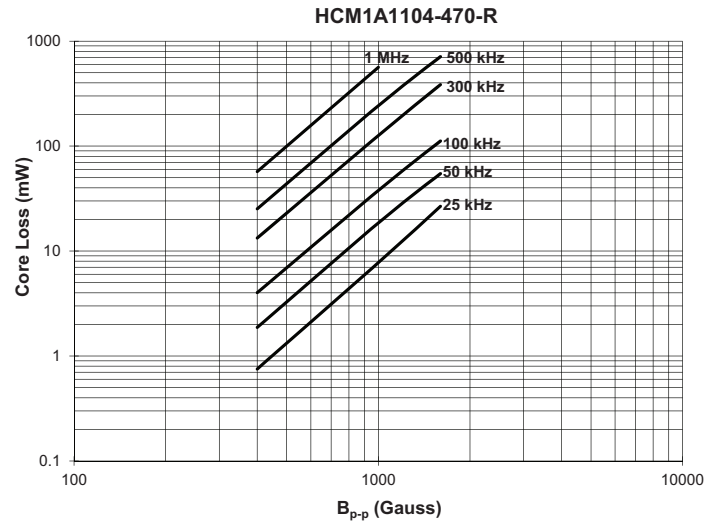
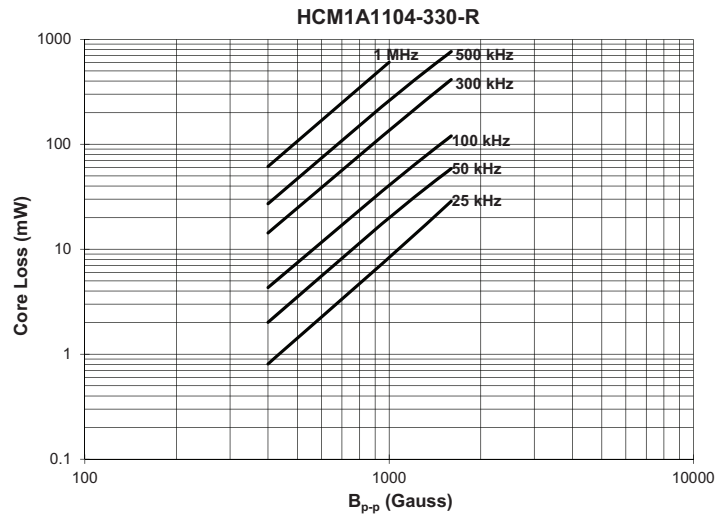
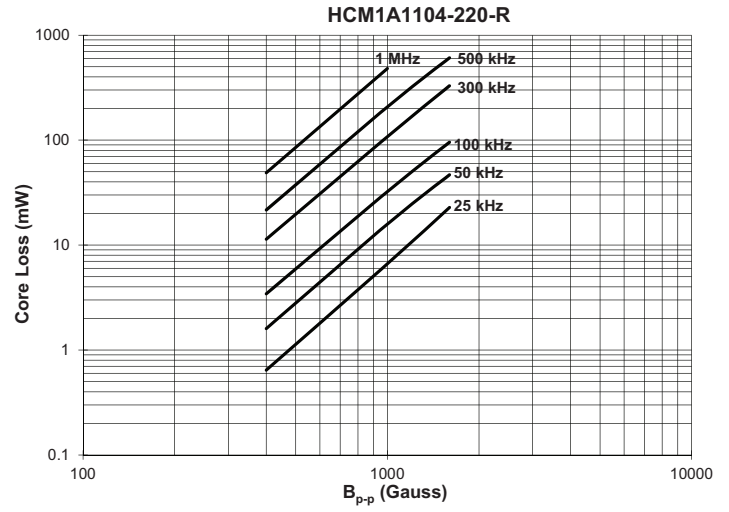
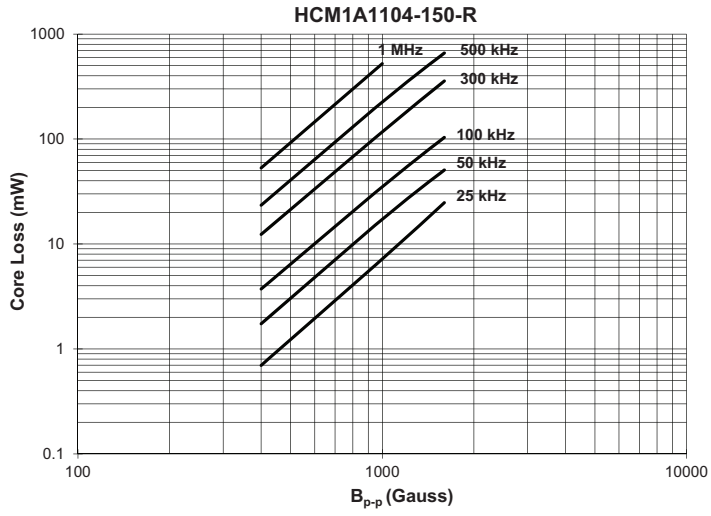
Core loss vs  $B_{p-p}$



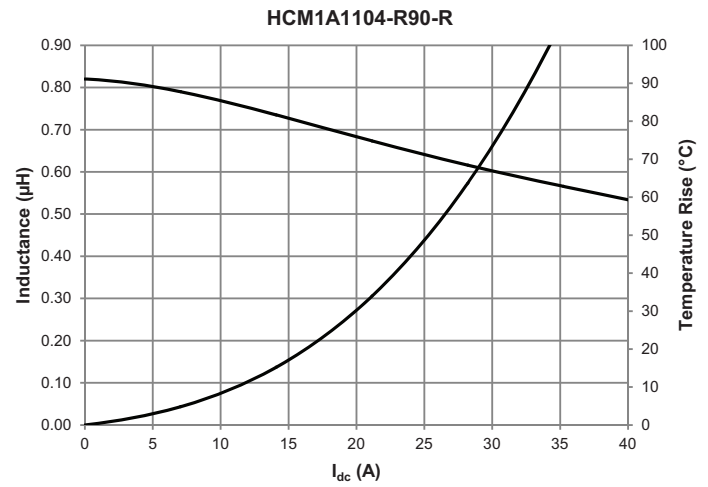
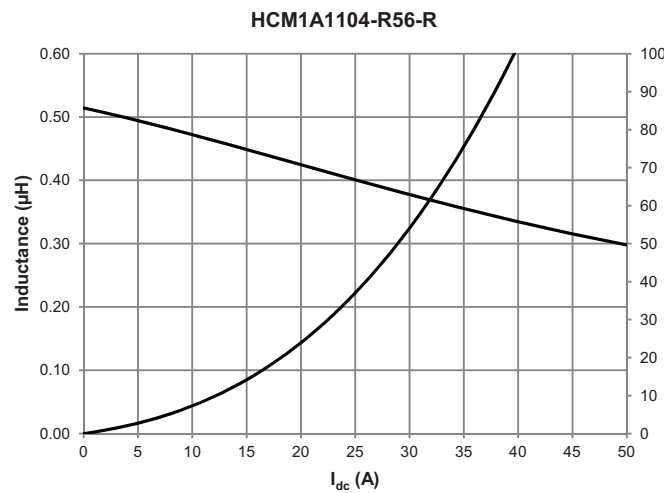
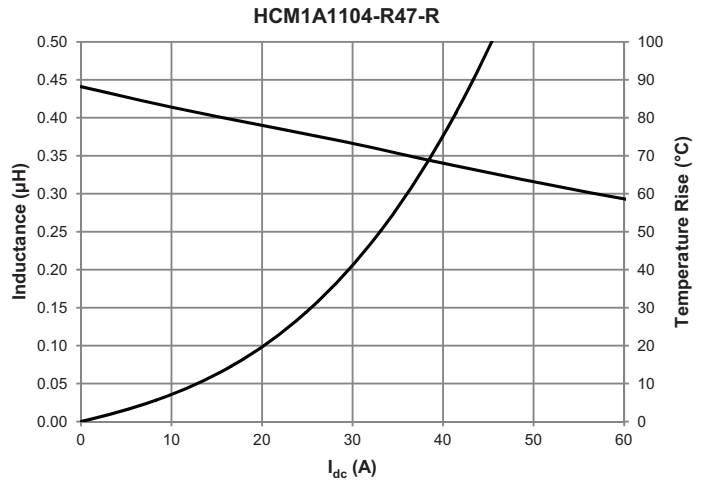
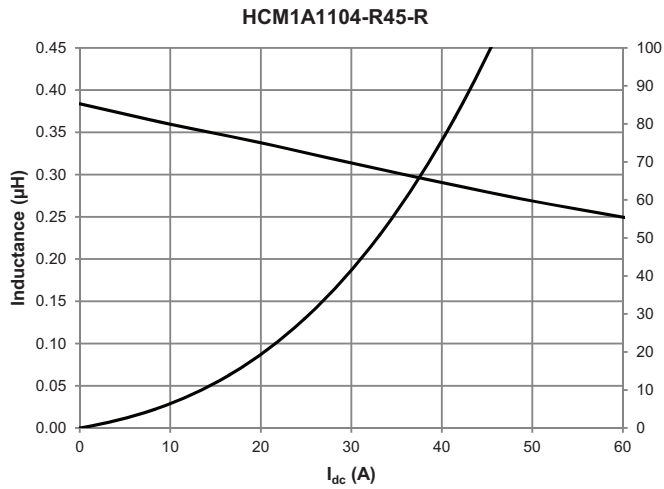
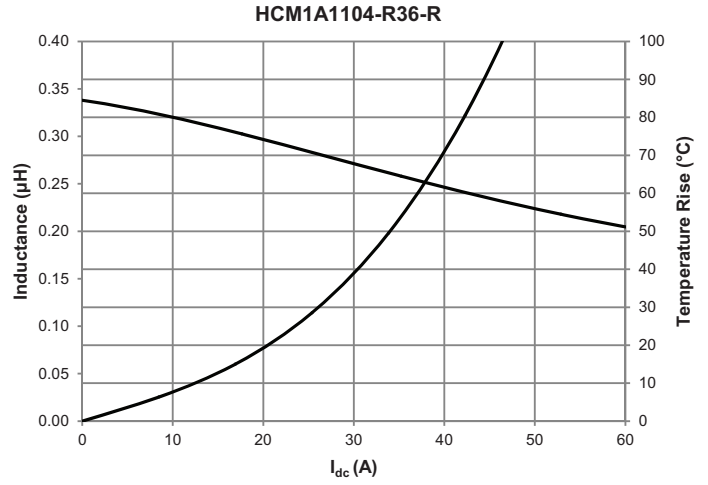
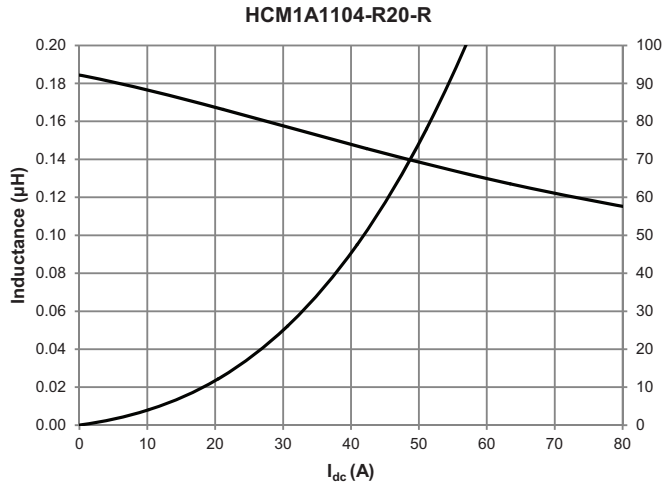
Core loss vs  $B_{p-p}$



Core loss vs  $B_{p-p}$

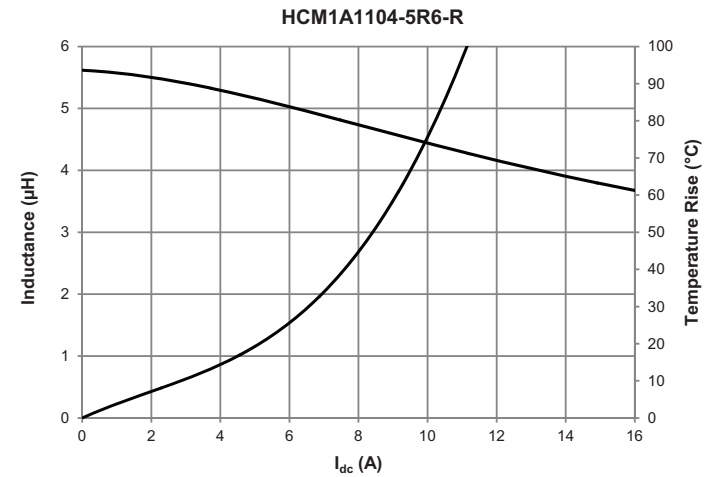
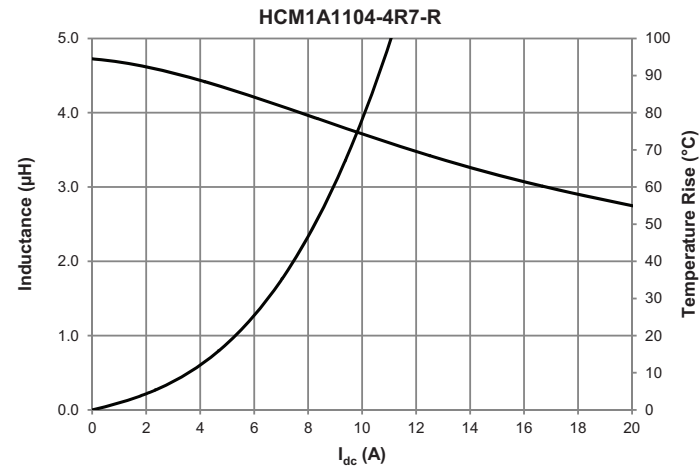
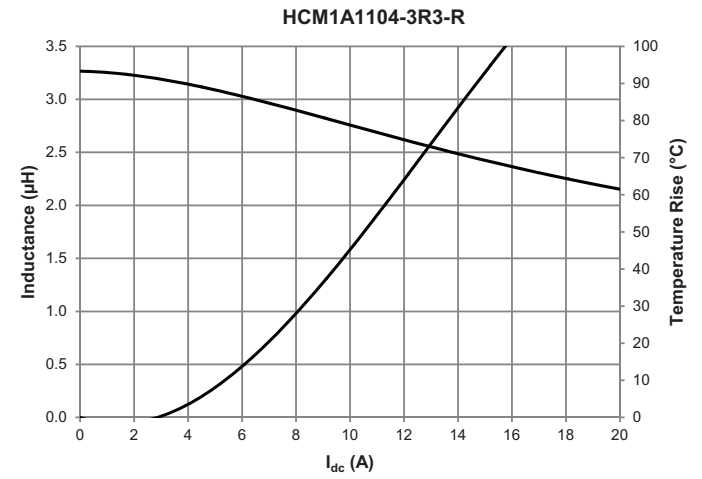
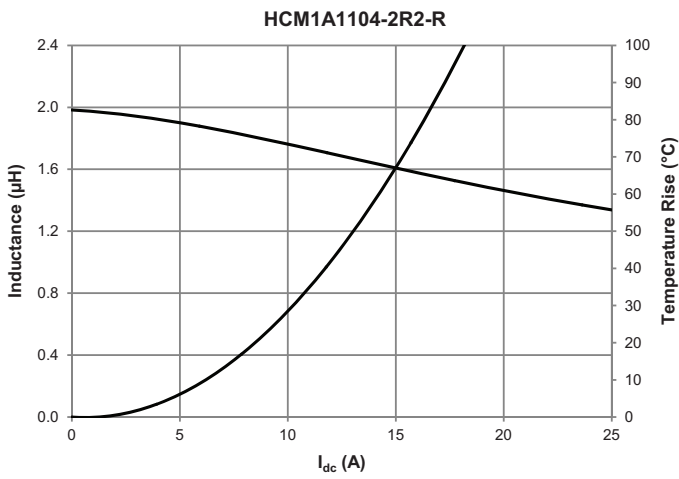
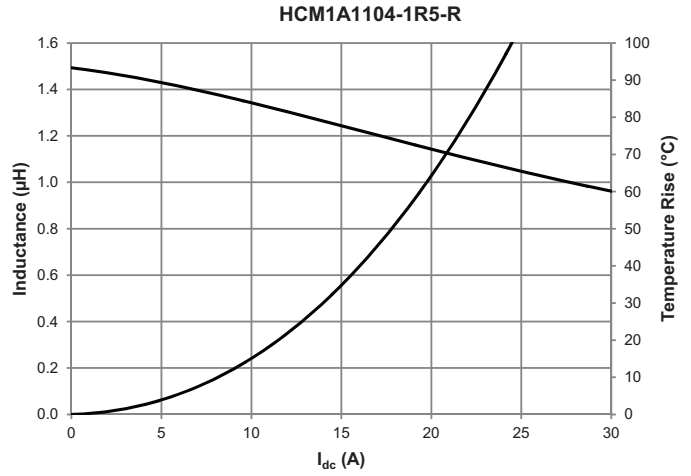
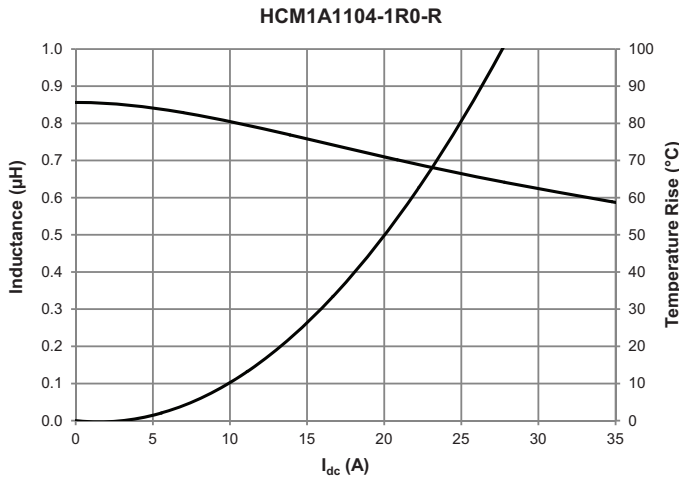


Inductance and temperature rise vs. current

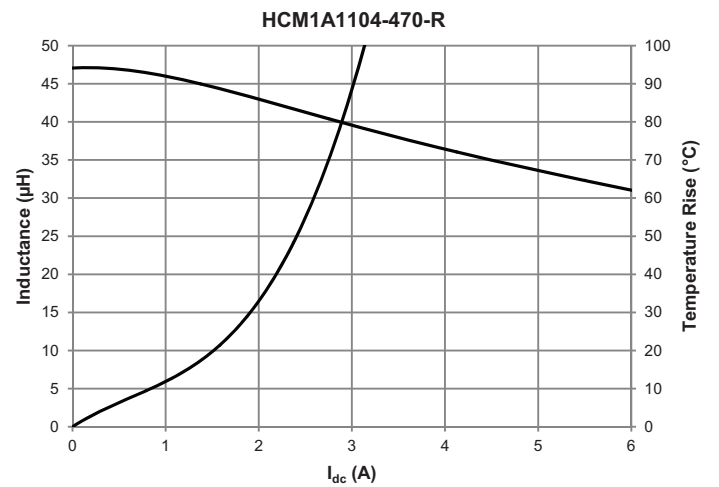
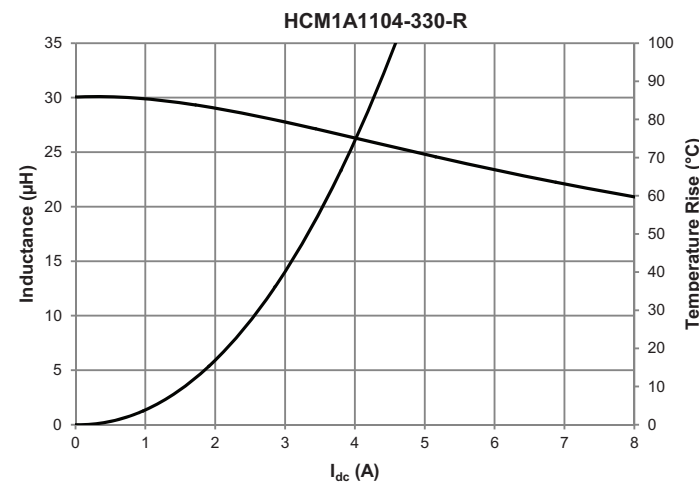
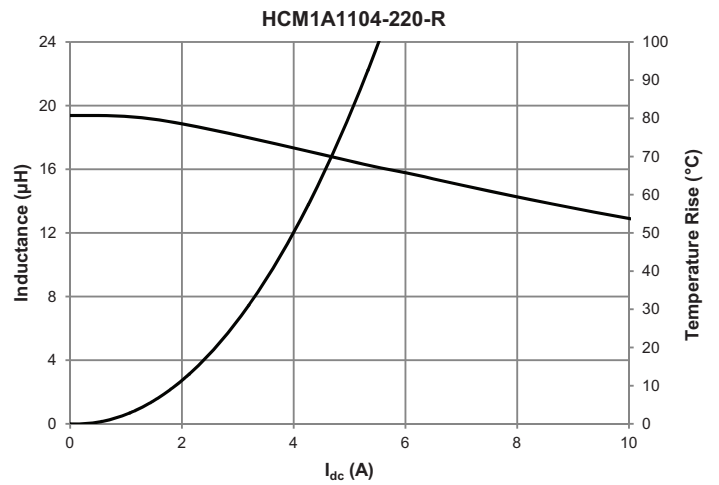
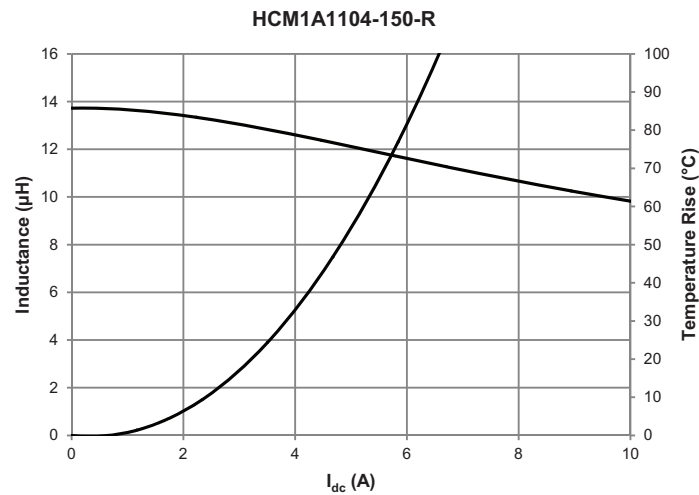
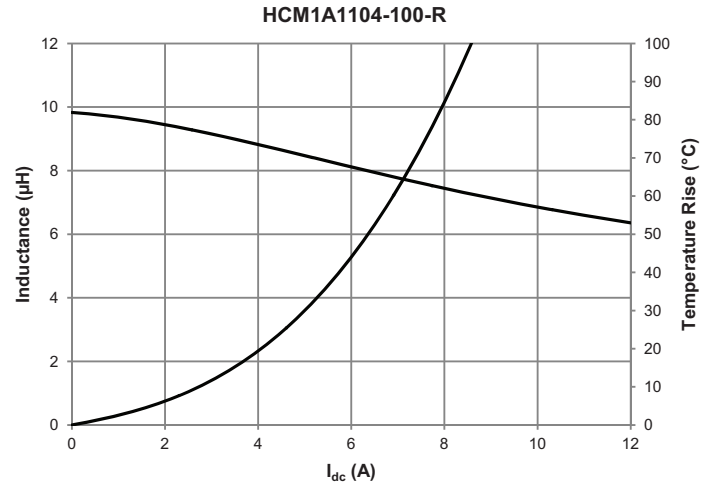
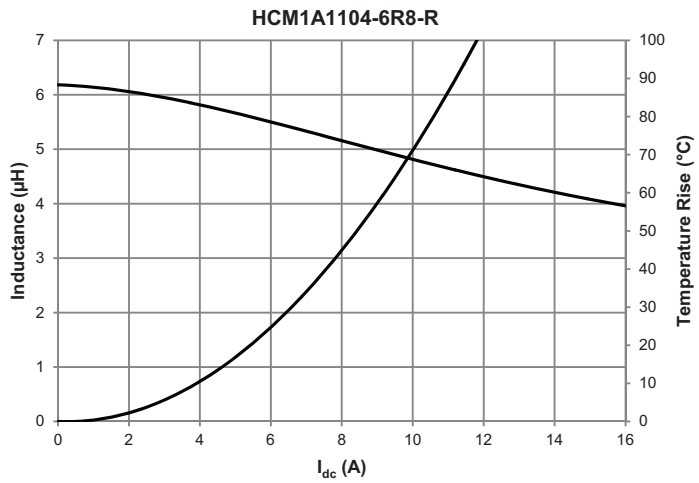




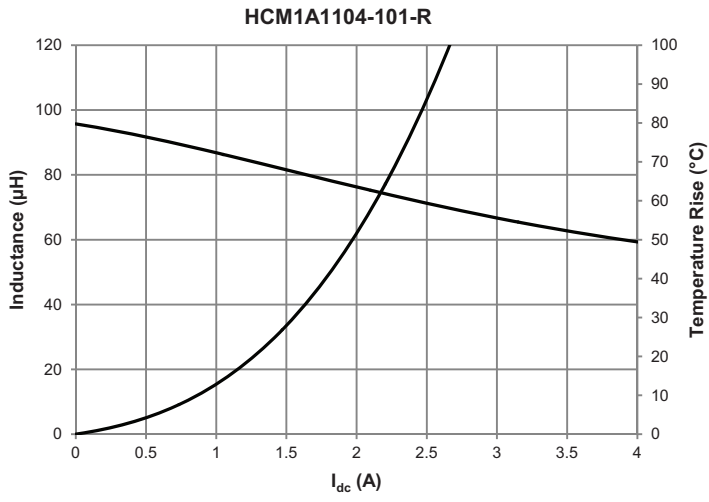
Inductance and temperature rise vs. current



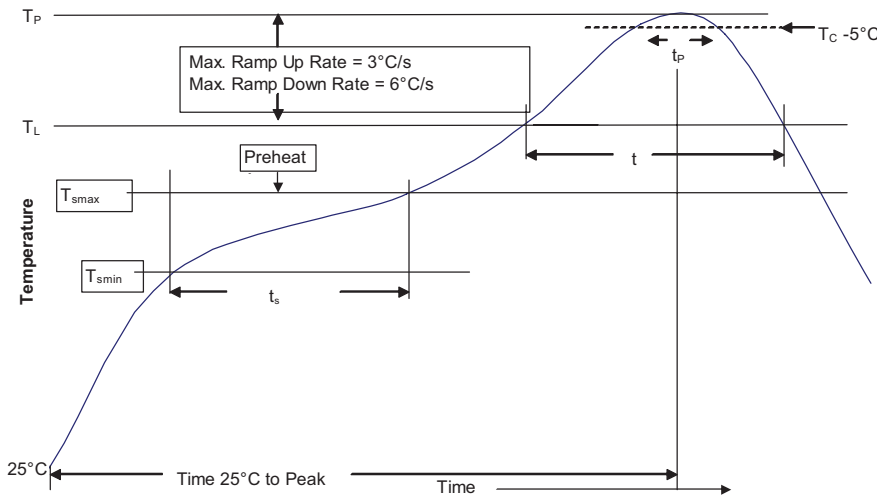
Inductance and temperature rise vs. current



**Inductance and temperature rise vs. current**



**Solder reflow profile**



**Table 1 - Standard SnPb Solder (T<sub>C</sub>)**

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

**Table 2 - Lead (Pb) Free Solder (T<sub>C</sub>)**

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350 - 2000	Volume mm <sup>3</sup> >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

**Reference JDEC J-STD-020**

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T <sub>smin</sub> )	100°C	150°C
• Temperature max. (T <sub>smax</sub> )	150°C	200°C
• Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	60-120 Seconds	60-120 Seconds
Average ramp up rate T <sub>smax</sub> to T <sub>p</sub>	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T <sub>L</sub> )	183°C	217°C
Time at liquidous (t <sub>L</sub> )	60-150 Seconds	60-150 Seconds
Peak package body temperature (T <sub>p</sub> )*	Table 1	Table 2
Time (t <sub>p</sub> )** within 5 °C of the specified classification temperature (T <sub>C</sub> )	20 Seconds**	30 Seconds**
Average ramp-down rate (T <sub>p</sub> to T <sub>smax</sub> )	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

\* Tolerance for peak profile temperature (T<sub>p</sub>) is defined as a supplier minimum and a user maximum.  
\*\* Tolerance for time at peak profile temperature (t<sub>p</sub>) is defined as a supplier minimum and a user maximum.

Life Support Policy: Eaton does not authorize the use of any of its products for use in life support devices or systems without the express written approval of an officer of the Company. Life support systems are devices which support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

Eaton reserves the right, without notice, to change design or construction of any products and to discontinue or limit distribution of any products. Eaton also reserves the right to change or update, without notice, any technical information contained in this bulletin.

**Eaton**  
**Electronics Division**  
 1000 Eaton Boulevard  
 Cleveland, OH 44122  
 United States  
[www.eaton.com/electronics](http://www.eaton.com/electronics)

© 2016 Eaton  
 All Rights Reserved  
 Publication No. 10550 BU-MC16071  
 August 2016

Eaton is a registered trademark.  
 All other trademarks are property of their respective owners.

